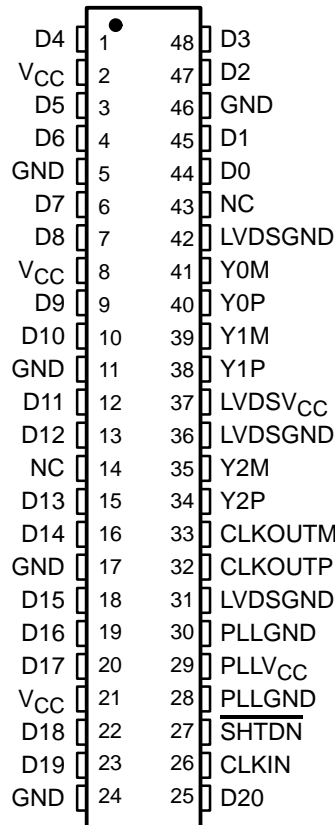


- **21:3 Data Channel Compression at up to 196 Million Bytes per Second Throughput**
- **Suited for SVGA, XGA, or SXGA Data Transmission From Controller to Display With Very Low EMI**
- **21 Data Channels Plus Clock In Low-Voltage TTL Inputs and 3 Data Channels Plus Clock Out Low-Voltage Differential Signaling (LVDS) Outputs**
- **Operates From a Single 3.3-V Supply and 89 mW (Typ)**
- **Ultralow-Power 3.3-V CMOS Version of the SN75LVDS84. Power Consumption About One Third of the 'LVDS84**
- **Packaged in Thin Shrink Small-Outline Package (TSSOP) With 20 Mil Terminal Pitch**
- **Consumes Less Than 0.54 mW When Disabled**
- **Wide Phase-Lock Input Frequency Range: 31 MHz to 75 MHz**
- **No External Components Required for PLL**
- **Outputs Meet or Exceed the Requirements of ANSI EIA/TIA-644 Standard**
- **SSC Tracking Capability of 3% Center Spread at 50-kHz Modulation Frequency**
- **Improved Replacement for SN75LVDS84 and NSC's DS90CF363A 3-V Device**
- **Available in Q-Temp Automotive High Reliability Automotive Applications Configuration Control / Print Support Qualification to Automotive Standards**

**DGG PACKAGE  
(TOP VIEW)**



NC – Not Connected

## description

The SN75LVDS84A and SN65LVDS84AQ FlatLink transmitters contains three 7-bit parallel-load serial-out shift registers, and four low-voltage differential signaling (LVDS) line drivers in a single integrated circuit. These functions allow 21 bits of single-ended LVTTTL data to be synchronously transmitted over 3 balanced-pair conductors for receipt by a compatible receiver, such as the SN75LVDS82 or SN75LVDS86/86A.

When transmitting, data bits D0 – D20 are each loaded into registers of the 'LVDS84A upon the falling edge. The internal PLL is frequency-locked to CLKIN and then used to unload the data registers in 7-bit slices. The three serial streams and a phase-locked clock (CLKOUT) are then output to LVDS output drivers. The frequency of CLKOUT is the same as the input clock, CLKIN.



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# SN75LVDS84A, SN65LVDS84AQ FLATLINK™ TRANSMITTER

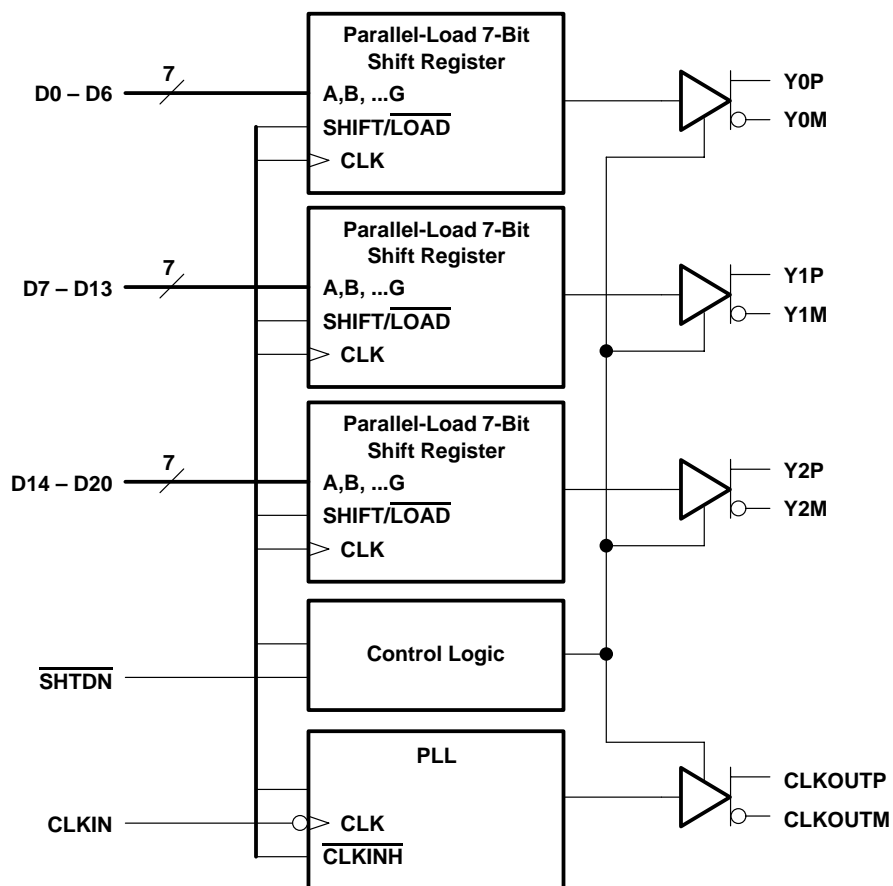
SLLS354E – MAY 1999 – REVISED JANUARY 2001

## description (continued)

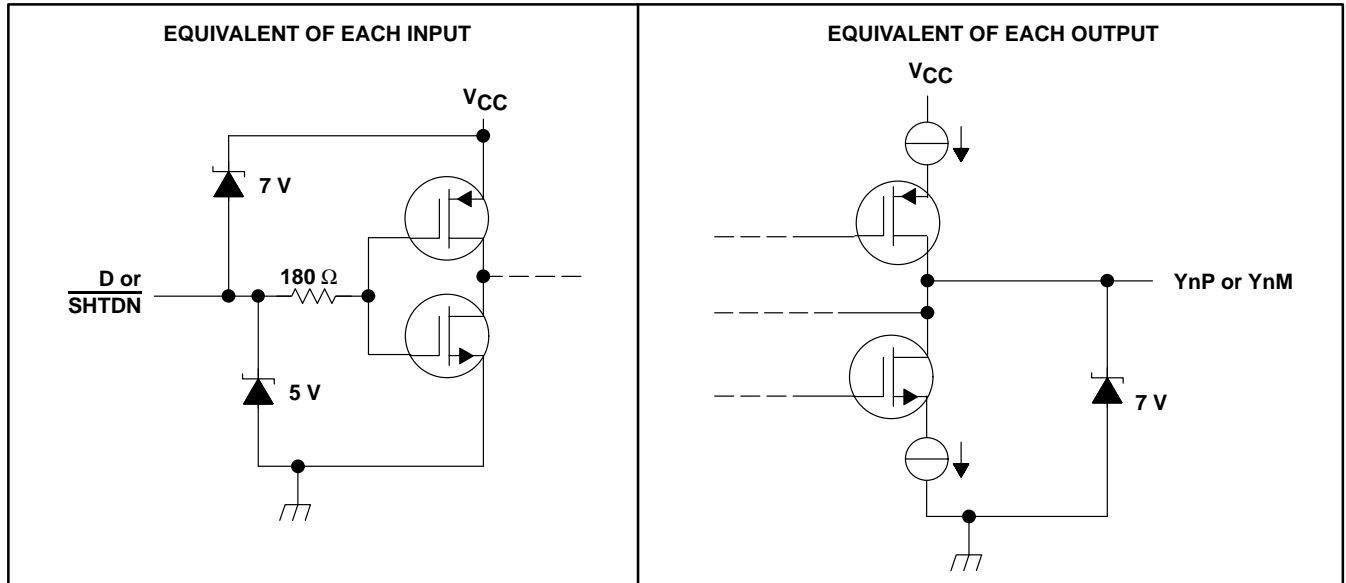
The 'LVDS84A requires no external components and little or no control. The data bus appears the same at the input to the transmitter and output of the receiver with the data transmission transparent to the user(s). The only user intervention is the possible use of the shutdown/clear ( $\overline{\text{SHTDN}}$ ) active-low input to inhibit the clock and shut off the LVDS output drivers for lower power consumption. A low-level on this signal clears all internal registers to a low level.

The SN75LVDS84A is characterized for operation over ambient free-air temperatures of 0°C to 70°C. The SN65LVDS84AQ is characterized for operation over the full Automotive temperature range of -40°C to 125°C.

## functional block diagram



schematics of input and output



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, $V_{CC}$ (see Note 1) .....	-0.5 V to 4 V
Input and output voltage ranges, $V_I$ , $V_O$ (all terminals) .....	-0.5 V to $V_{CC} + 0.5$ V
Continuous total power dissipation .....	See Dissipation Rating Table
Operating virtual junction temperature range, $T_J$ .....	-40°C to 150°C
Electrostatic discharge: ESD machine model .....	200 V
ESD human-body model .....	6000 V
ESD charged-device model .....	1500 V
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds .....	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to the GND terminals.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR‡ ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
DGG	1637 mW	13.1 mW/°C	1048 mW	327 mW

‡ This is the inverse of the junction-to-ambient thermal resistance when board mounted and with no air flow.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, $V_{CC}$	3	3.3	3.6	V
High-level input voltage, $V_{IH}$	2			V
Low-level input voltage, $V_{IL}$			0.8	V
Differential load impedance, $Z_L$	90		132	$\Omega$
Operating free-air temperature, $T_A$			0	°C
			70	
			-40	
			125	

# SN75LVDS84A, SN65LVDS84AQ FLATLINK™ TRANSMITTER

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## timing requirements

	MIN	NOM	MAX	UNIT
$t_C$ Input clock period	13.3	$t_C$	32.4	ns
$t_W$ Pulse duration, high-level input clock	$0.4t_C$		$0.6t_C$	ns
$t_t$ Transition time, input signal			5	ns
$t_{SU}$ Setup time, data, D0 – D20 valid before CLKIN↓ (see Figure 2)	3			ns
$t_H$ Hold time, data, D0 – D20 valid after CLKIN↓ (see Figure 2)	1.5			ns

## electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$V_{IT}$ Input threshold voltage			1.4		V
$ V_{OD} $ Differential steady-state output voltage magnitude	$R_L = 100 \Omega$ , See Figure 3	247		454	mV
$\Delta V_{OD} $ Change in the steady-state differential output voltage magnitude between opposite binary states				50	mV
$V_{OC(SS)}$ Steady-state common-mode output voltage	$R_L = 100 \Omega$ , See Figure 3	1.125		1.375	V
$V_{OC(PP)}$ Peak-to-peak common-mode output voltage			80	150	mV
$I_{IH}$ High-level input current	$V_{IH} = V_{CC}$	SN75LVDS84A		20	$\mu A$
		SN65LVDS84AQ		25	
$I_{IL}$ Low-level input current	$V_{IL} = 0$			$\pm 10$	$\mu A$
$I_{OS}$ Short-circuit output current	$V_{O(Yn)} = 0$		-6	$\pm 24$	mA
	$V_{OD} = 0$		-6	$\pm 12$	
$I_{OZ}$ High-impedance output current	$V_O = 0$ to $V_{CC}$			$\pm 10$	$\mu A$
$I_{CC(AVG)}$ Quiescent supply current (average)	Disabled, All inputs at GND	SN75LVDS84A	15	150	$\mu A$
		SN65LVDS84AQ	15	170	
	Enabled, $R_L = 100 \Omega$ (4 places) Gray-scale pattern (see Figure 4)	$f = 65$ MHz	27	35	mA
		$f = 75$ MHz	30	38	
	Enabled, $R_L = 100 \Omega$ , (4 places) Worst-case pattern (see Figure 5)	$f = 65$ MHz	28	36	
		$f = 75$ MHz	31	39	
$C_I$ Input capacitance			2		pF

† All typical values are at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ C$ .



switching characteristics over recommended operating conditions (unless otherwise noted)

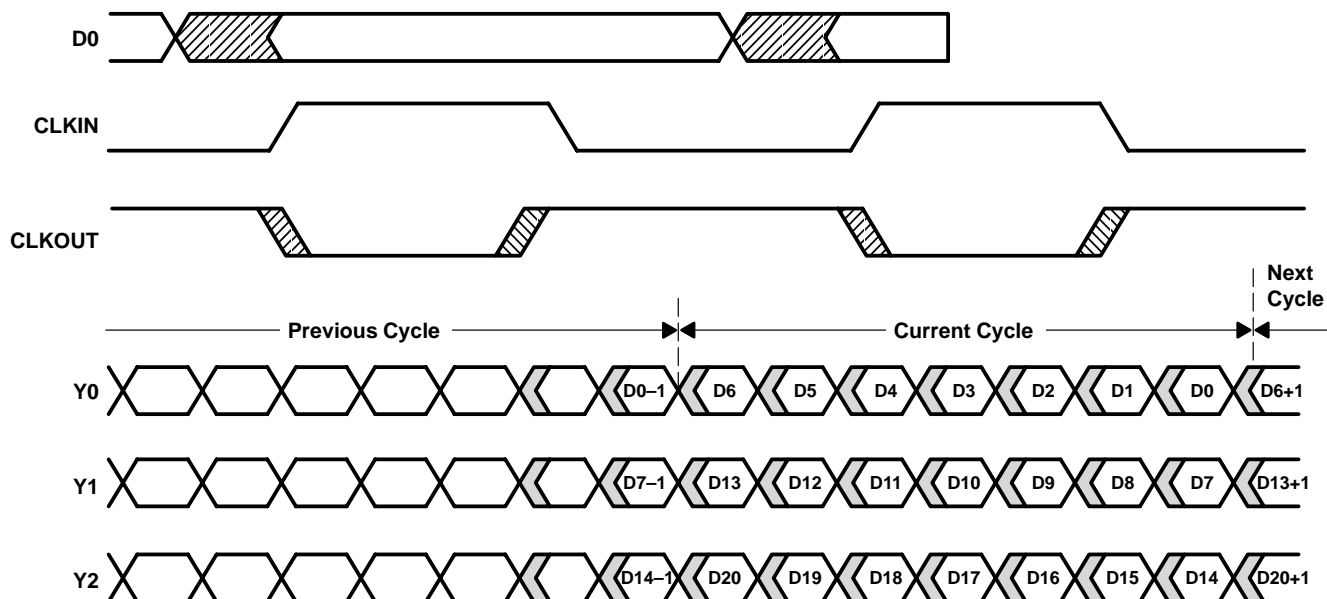
PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t <sub>d0</sub>	Delay time, CLKOUT↑ to serial bit position 0	-0.2		0.2	ns
t <sub>d1</sub>	Delay time, CLKOUT↑ to serial bit position 1	$\frac{1}{7}t_c - 0.2$	$\frac{1}{7}t_c + 0.2$		
t <sub>d2</sub>	Delay time, CLKOUT↑ to serial bit position 2	$\frac{2}{7}t_c - 0.2$	$\frac{2}{7}t_c + 0.2$		
t <sub>d3</sub>	Delay time, CLKOUT↑ to serial bit position 3	$\frac{3}{7}t_c - 0.2$	$\frac{3}{7}t_c + 0.2$		
t <sub>d4</sub>	Delay time, CLKOUT↑ to serial bit position 4	$\frac{4}{7}t_c - 0.2$	$\frac{4}{7}t_c + 0.2$		
t <sub>d5</sub>	Delay time, CLKOUT↑ to serial bit position 5	$\frac{5}{7}t_c - 0.2$	$\frac{5}{7}t_c + 0.2$		
t <sub>d6</sub>	Delay time, CLKOUT↑ to serial bit position 6	$\frac{6}{7}t_c - 0.2$	$\frac{6}{7}t_c + 0.2$		
t <sub>sk(o)</sub>	Output skew, $t_n - \frac{n}{7}t_c$	-0.2		0.2	ns
t <sub>d7</sub>	Delay time, CLKIN↓ to CLKOUT↑	t <sub>c</sub> = 15.38 ns (± 0.2%),  Input clock jitter  < 50 ps‡, See Figure 6		2.7	ns
		t <sub>c</sub> = 13.33 ns ~ 32.25 ns (± 0.2%),  Input clock jitter  < 50 ps‡, See Figure 6		1 4.5	
Δt <sub>c(o)</sub>	Cycle time, output clock jitter§	t <sub>c</sub> = 15.38 + 0.308 sin (2π500E3t) ± 0.05 ns, See Figure 7		±62	ps
		t <sub>c</sub> = 15.38 + 0.308 sin (2π3E6t) ± 0.05 ns, See Figure 7		±121	
t <sub>w</sub>	Pulse duration, high-level output clock		$\frac{4}{7}t_c$		ns
t <sub>t</sub>	Transition time, differential output voltage (t <sub>r</sub> or t <sub>f</sub> )	See Figure 3	700	1500	ps
t <sub>en</sub>	Enable time, SHTDN↑ to phase lock (Y <sub>n</sub> valid)	See Figure 8	1		ms
t <sub>dis</sub>	Disable time, SHTDN↓ to off state (CLKOUT low)	See Figure 9	6.5		ns

† All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

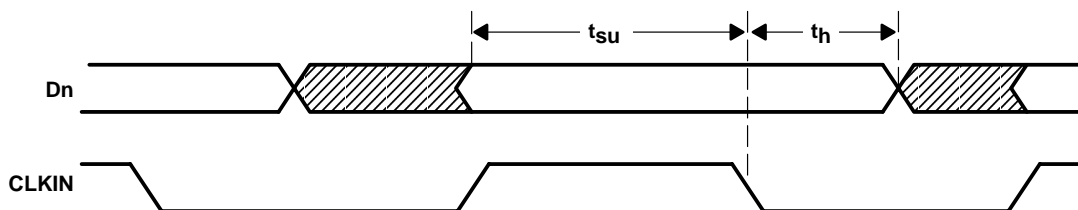
‡ |Input clock jitter| is the magnitude of the change in the input clock period.

§ Output clock jitter is the change in the output clock period from one cycle to the next cycle observed over 15000 cycles.

**PARAMETER MEASUREMENT INFORMATION**

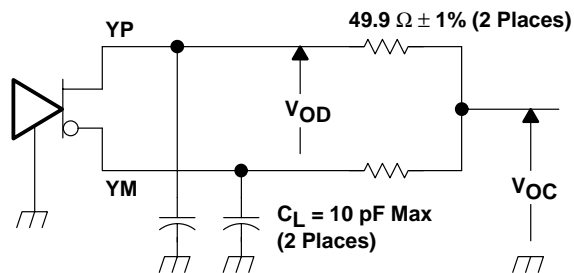


**Figure 1. Typical Load and Shift Sequences**



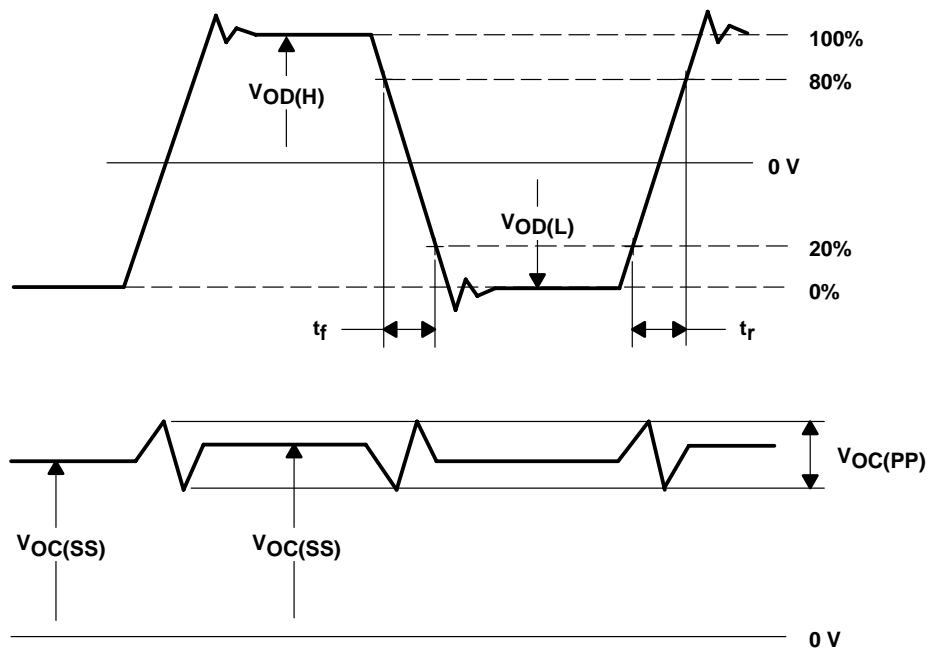
NOTE A: All input timing is defined at 1.4 V on an input signal with a 10%-to-90% rise or fall time of less than 5 ns.

**Figure 2. Setup and Hold Time Definition**



NOTE A: The lumped instrumentation capacitance for any single-ended voltage measurement is less than or equal to 10 pF. When making measurements at YP or YM, the complementary output is similarly loaded.

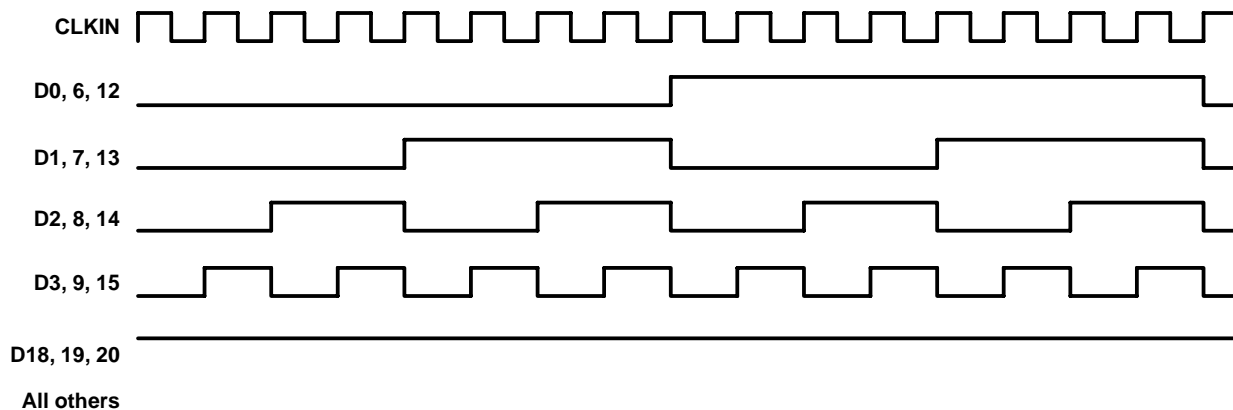
(a) SCHEMATIC



(b) WAVEFORMS

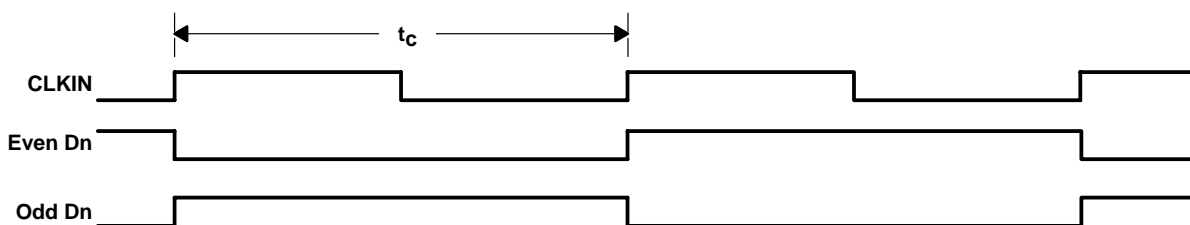
Figure 3. Test Load and Voltage Definitions for LVDS Outputs

**PARAMETER MEASUREMENT INFORMATION**



NOTES: A. The 16-grayscale test-pattern test device power consumption for a typical display pattern.  
 B.  $V_{IH} = 2\text{ V}$  and  $V_{IL} = 0.8\text{ V}$

**Figure 4. 16-Grayscale Test-Pattern Waveforms**



NOTES: A. The worst-case test pattern produces nearly the maximum switching frequency for all of the LVDS outputs.  
 B.  $V_{IH} = 2\text{ V}$  and  $V_{IL} = 0.8\text{ V}$

**Figure 5. Worst-Case Test-Pattern Waveforms**



PARAMETER MEASUREMENT INFORMATION

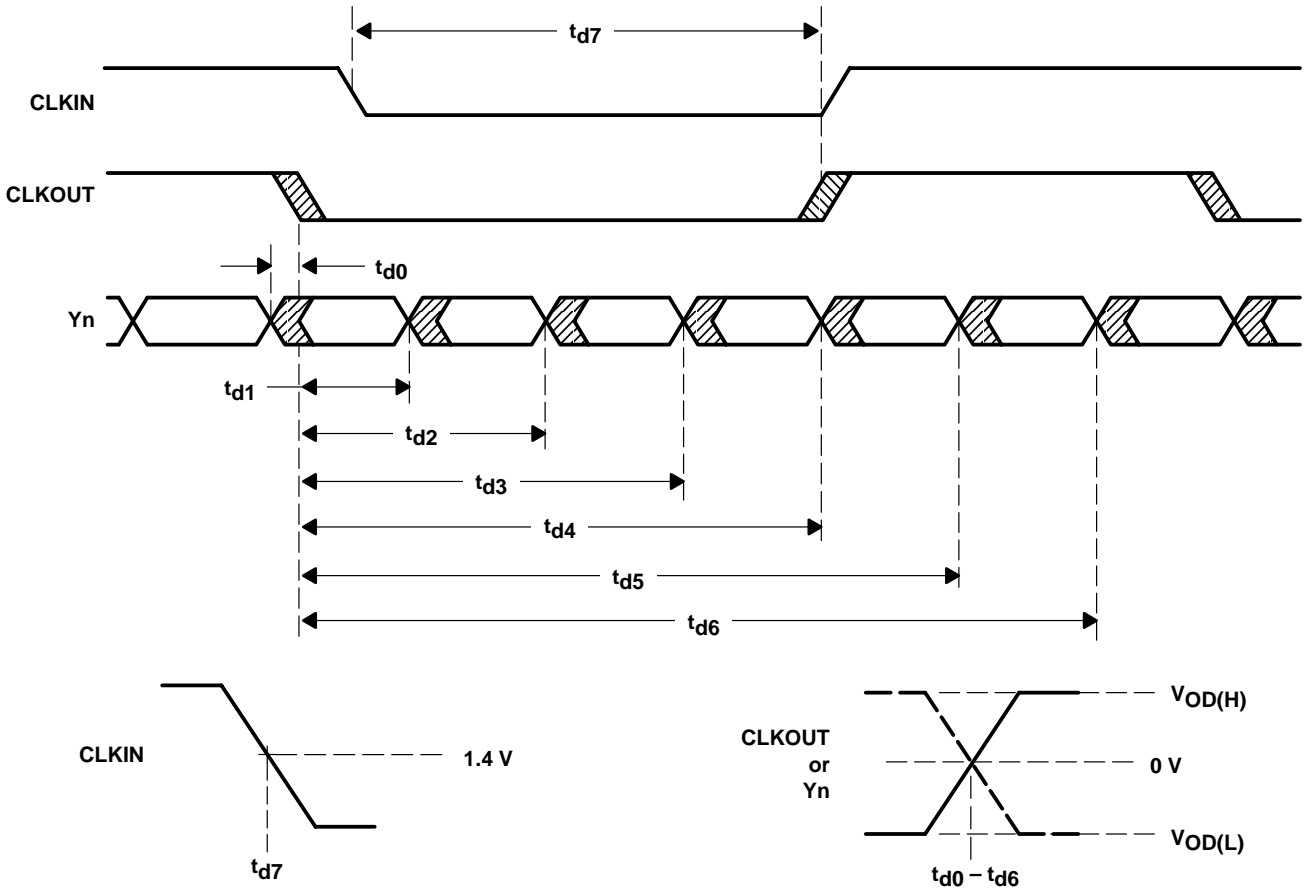


Figure 6. Timing Definitions

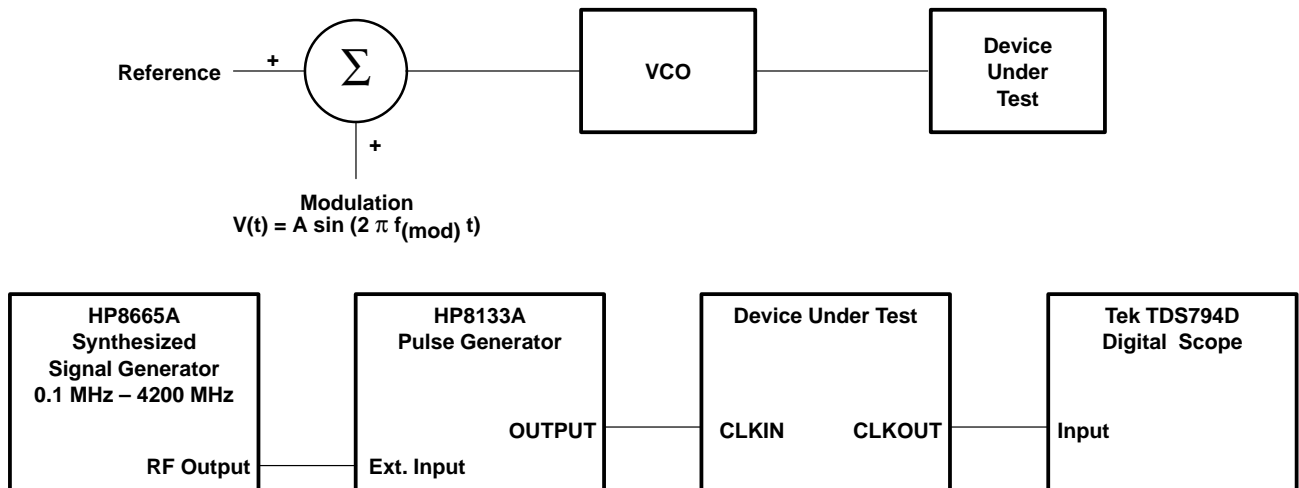
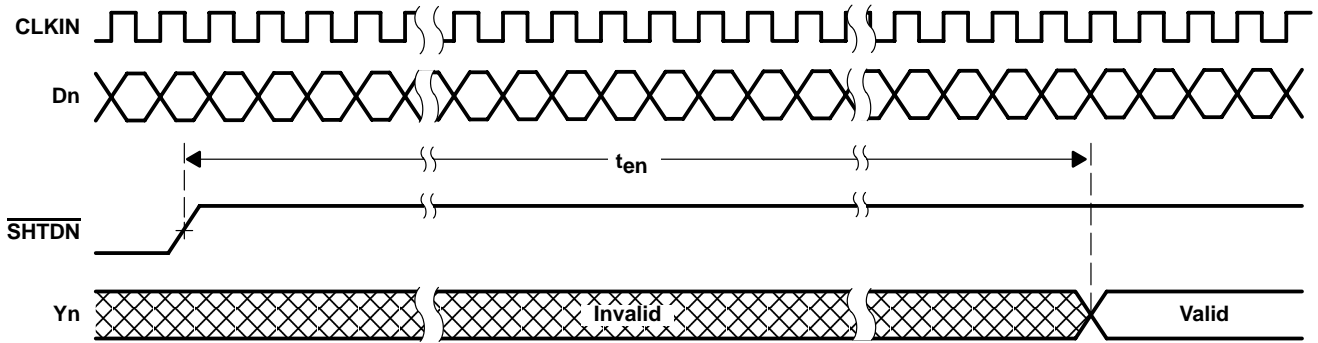
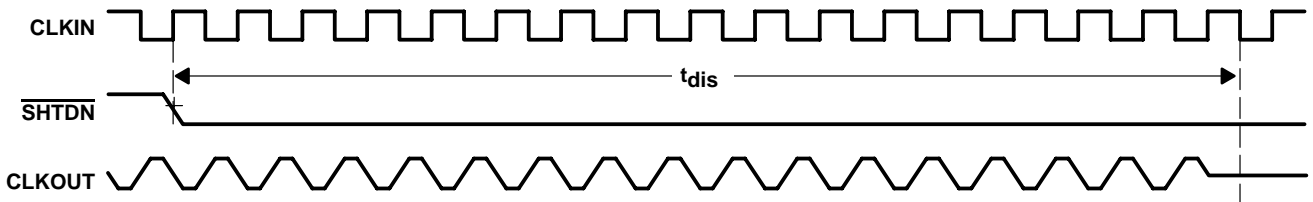


Figure 7. Clock Jitter Test Setup

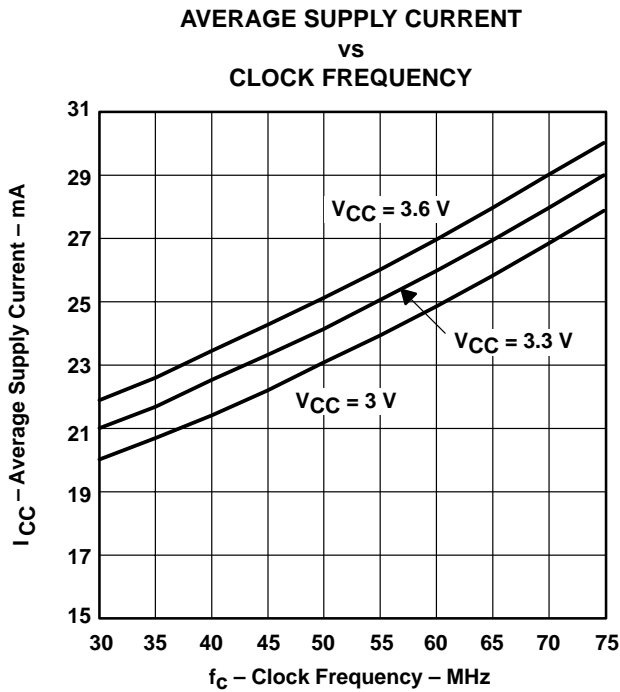
**TYPICAL CHARACTERISTICS**



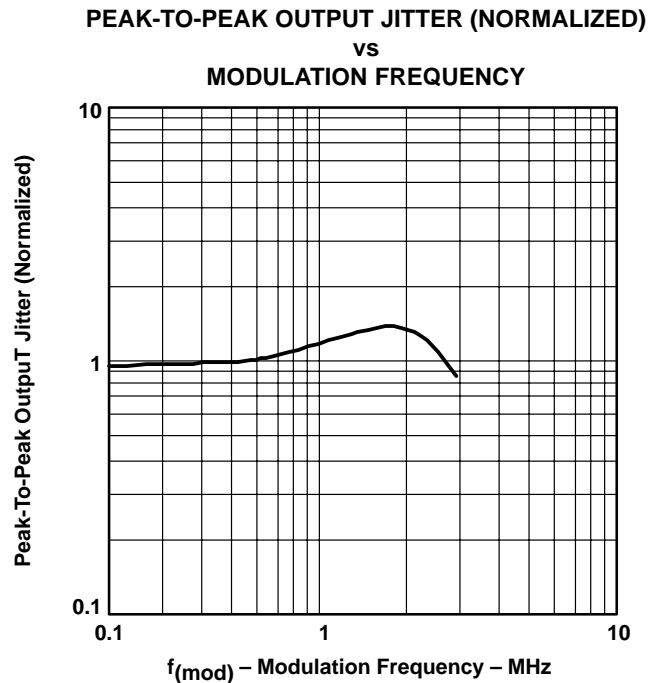
**Figure 8. Enable Time Waveforms**



**Figure 9. Disable Time Waveforms**

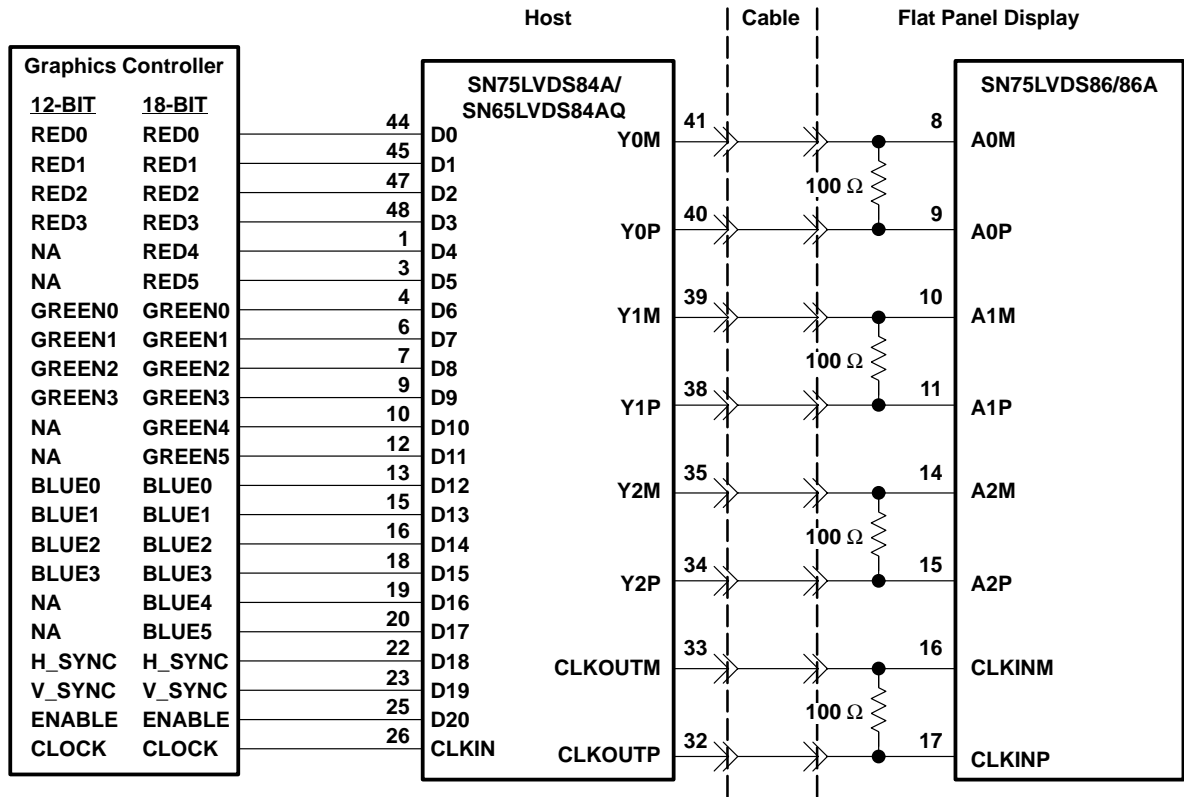


**Figure 10. Grayscale Input Pattern**



**Figure 11. Output Period Jitter vs Modulation Frequency**

APPLICATION INFORMATION



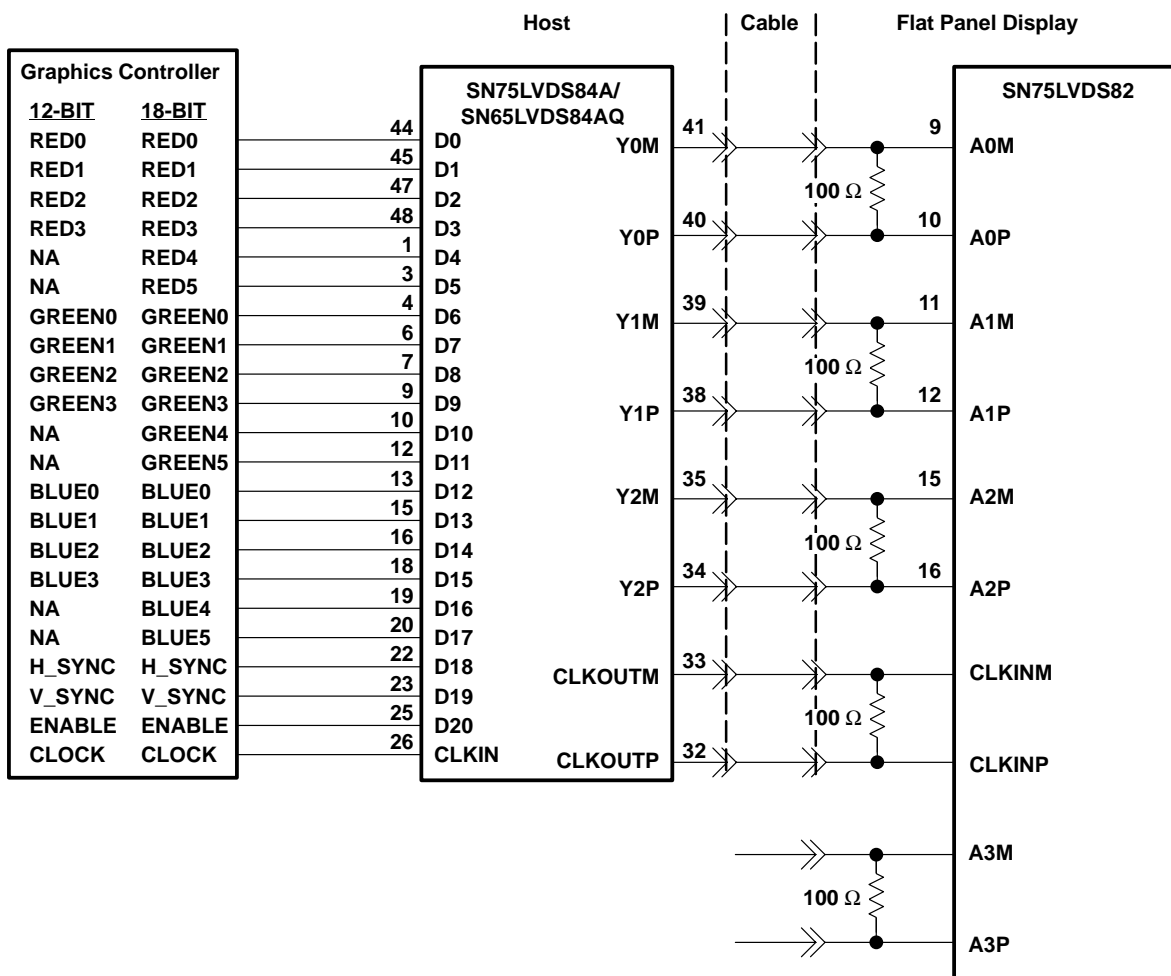
- NOTES: A. The five 100-Ω terminating resistors are recommended to be 0603 types.  
 B. NA – not applicable, these unused inputs should be left open.

Figure 12. Color Host to LCD Panel Application

# SN75LVDS84A, SN65LVDS84AQ FLATLINK™ TRANSMITTER

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## APPLICATION INFORMATION



- NOTES: A. The four 100-Ω terminating resistors are recommended to be 0603 types.  
 B. NA – not applicable, these unused inputs should be left open.

Figure 13. 18-Bit Color Host to 24-Bit LCD Display Panel Application

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN65LVDS84AQDGG	ACTIVE	TSSOP	DGG	48	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	65LVDS84AQ	<a href="#">Samples</a>
SN65LVDS84AQDGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	65LVDS84AQ	<a href="#">Samples</a>
SN75LVDS84ADGG	ACTIVE	TSSOP	DGG	48	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	SN75LVDS84A	<a href="#">Samples</a>
SN75LVDS84ADGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	SN75LVDS84A	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

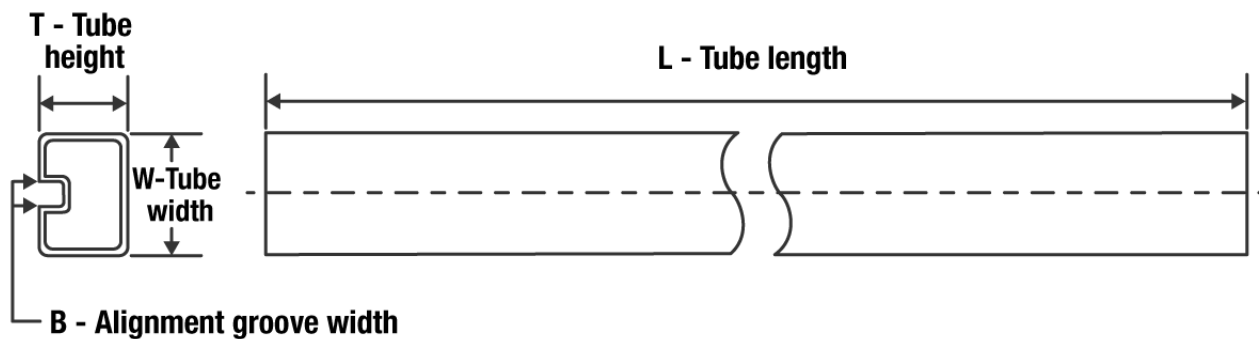
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LVDS84AQDGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN75LVDS84ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LVDS84AQDGGR	TSSOP	DGG	48	2000	350.0	350.0	43.0
SN75LVDS84ADGGR	TSSOP	DGG	48	2000	350.0	350.0	43.0



**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN65LVDS84AQDGG	DGG	TSSOP	48	40	530	11.89	3600	4.9
SN75LVDS84ADGG	DGG	TSSOP	48	40	530	11.89	3600	4.9

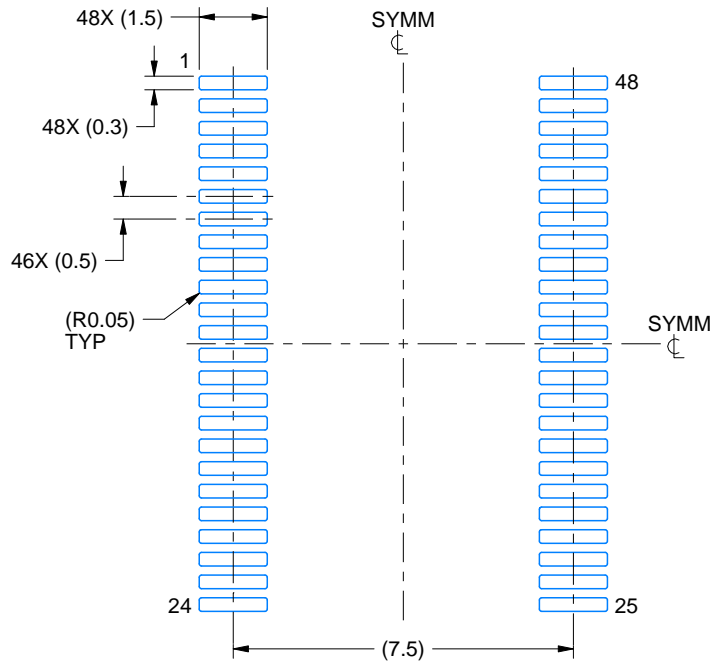


# EXAMPLE BOARD LAYOUT

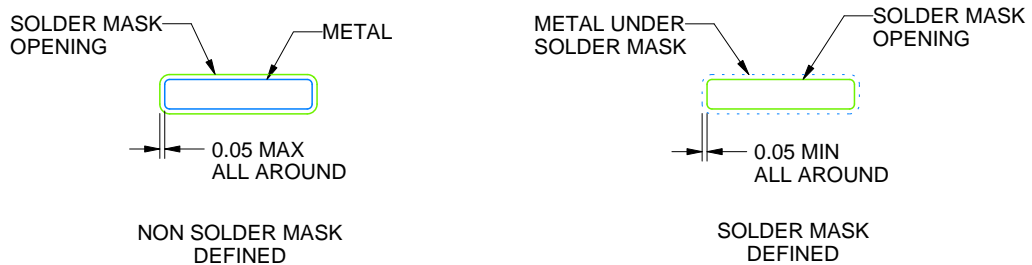
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4214859/B 11/2020

NOTES: (continued)

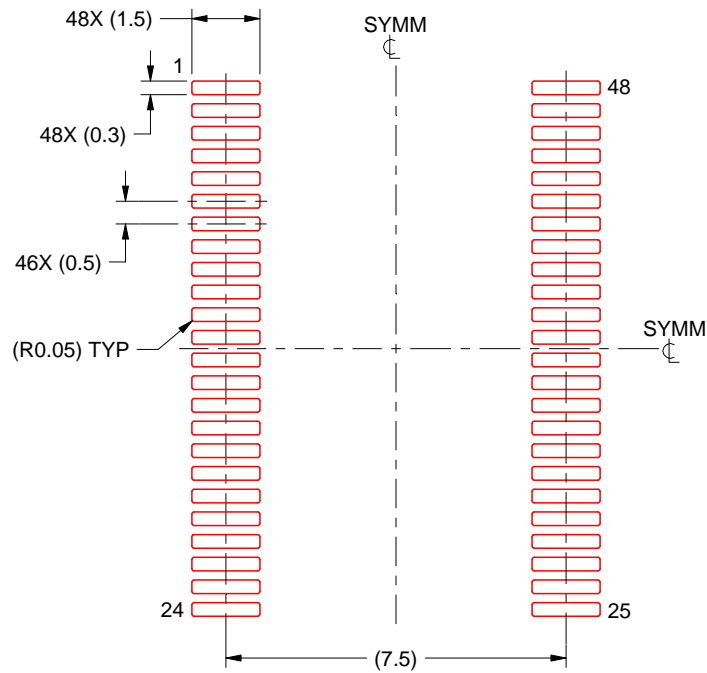
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4214859/B 11/2020

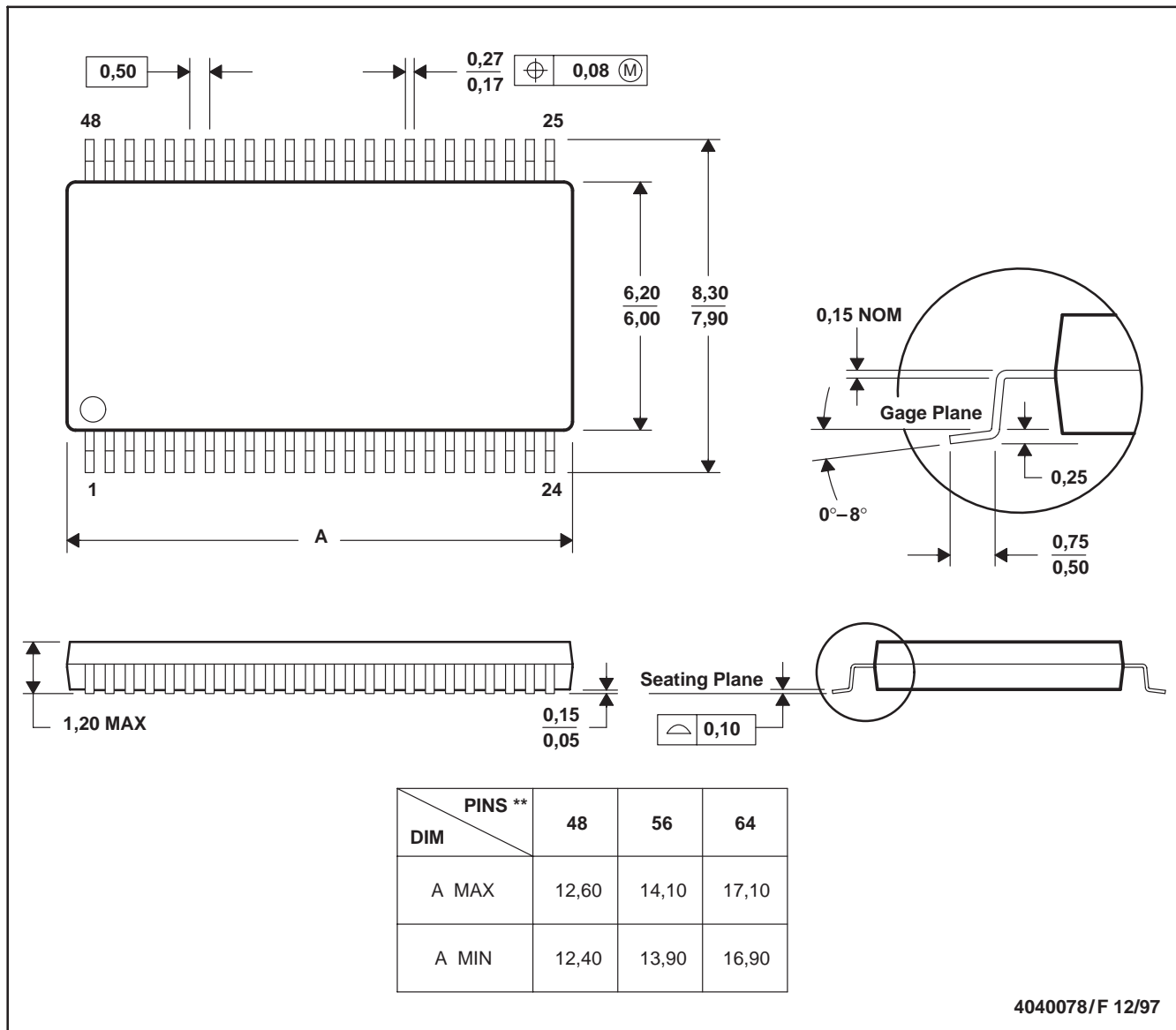
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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